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Customer Information Notification | 201808017I

Issue Date: 30-Aug-2018
Effective Date: 31-Aug-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

QUALITY

Management Summary
The LPC8N04 has two MIFARE Product Type and Product Sub Type Numbers in the Electronic Die ID

Change Category

[ ] Wafer Fab Process	[ ] Assembly [ ] Product Marking Process	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly [ ] Mechanical Materials Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly [ ] Location Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - Electronic Die ID		

LPC8N04 Has Two MIFARE Product Type and Product Sub Type Numbers

Description

LPC8N04 has two MIFARE Product Type and Product Sub Type Numbers. The MIFARE Product information is used in the NFC SW to indicate the Product family to the NFC Host.

Information Notification: During manufacturing we have added another Product Type and Product Sub Type Number in the electronic die ID to identify LPC8N04 under the MIFARE family.

Date code 1829 and before:
Product type: 0x04
Product sub-type: 0x06

After date code 1829:
Product type: 0x09
Product sub-type: 0x02

Reason

This CIN serves to inform customers of the new Product Type and Product Sub Type number in the electronic die ID.
Identification of Affected Products
Top side marking
Date code 1829 and before:
Product type: 0x04
Product sub-type: 0x06

After date code 1829:
Product type: 0x09
Product sub-type: 0x02

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   Tim Camenzind
Position   Senior Quality Engineer
e-mail address   tim.camenzind@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC8N04FHI24Z	935359392515	LPC8N04FHI24	32-bit ARM Cortex-M0+	SOT616-3	HVQFN24	RFS	BL Microcontrollers
LPC8N04FHI24E	935359392551	LPC8N04FHI24	32-bit ARM Cortex-M0+	SOT616-3	HVQFN24	RFS	BL Microcontrollers